

PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Toshihiko MIYAZAKI

Serial No: Not assigned

Filed: February 12, 2004

For: Semiconductor Device and Method for
Manufacturing Semiconductor Device

Art Unit: Not assigned

Examiner: Not assigned

**TRANSMITTAL OF INFORMATION DISCLOSURE
STATEMENT**

Mail Stop PATENT APPLICATION
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

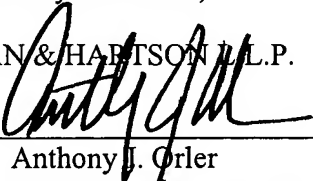
The information disclosure statement submitted herewith is being filed concurrently with the subject application [37 C.F.R. § 1.97(b)] and contains no items of information cited in any communication from a foreign patent office in a counterpart foreign application [37 C.F.R. § 1.97(e)(1)].

If it should be determined that for any reason either an insufficient or excessive fee has been paid, please charge any insufficiency or credit any overpayment necessary to ensure consideration of the information disclosure statement for the above-identified application to Deposit Account No. 50-1314. A copy of this paper is enclosed.

Respectfully submitted,

HOGAN & HARTSON LLP.

By: _____


Anthony J. Orler
Registration No. 41,232
Attorney for Applicant(s)

Date: February 12, 2004

500 South Grand Avenue, Suite 1900
Los Angeles, California 90071
Telephone: 213-337-6700
Facsimile: 213-337-6701

